

In the Claims

1. (currently amended) A printed circuit board (PCB) comprising:

 a first layer of electrically non-conductive material; and

 ~~a patterned~~ an electrically conductive ~~second~~ material disposed in contact with said first layer, said electrically conductive ~~second~~ material forming a patterned bond pad defining a channel therein facilitating outgassing of bubbles via the channel, said first layer of electrically non-conductive material exposed in said channel through said ~~patterned~~ pattern in said electrically conductive ~~second~~ material.
2. (cancelled)
3. (original) The PCB as specified in Claim 1 wherein said bond pad is dimensioned to define a plurality of said channels extending laterally through said bond pad.
4. (original) The PCB as specified in Claim 1 further comprising a plurality of pads disposed about said bond pad and being adapted to receive a multi-pin integrated circuit being centered over the bond pad.
5. (original) The PCB as specified in Claim 3 wherein said channels are defined in a radial pattern.
6. (original) The PCB as specified in Claim 5 wherein said radial lines terminate at a point distant from a focal point.
7. (original) The PCB as specified in Claim 6 wherein said radial lines have different lengths.

8. (withdrawn) The PCB as specified in Claim 6 wherein some of the radial lines terminate different distances from the focal point.

9. (original) The PCB as specified in Claim 4 wherein said channels are defined as multiple lines.

10. (withdrawn) The PCB as specified in Claim 9 wherein said channels are defined as parallel said lines.

11. (withdrawn) The PCB as specified in Claim 9 wherein said multiple lines intersect.

12. (currently amended) In combination;

an integrated circuit having a lower surface including an exposed solder pad;

a first layer of electrically non-conductive material; and

~~a patterned~~ an electrically conductive ~~second~~ material disposed in contact with said first layer and opposed to said solder pad, said ~~patterned~~ electrically conductive ~~second~~ material forming a bond pad having defining a channel pattern therein facilitating outgassing of bubbles via the channel, said first layer of electrically non-conductive material exposed in said channel through said ~~patterned~~ pattern in the electrically conductive ~~second~~ material.

13. (cancelled)

14. (original) The PCB as specified in Claim 12 wherein said bond pad is dimensioned to define a plurality of said channels extending laterally through said bond pad.

15. (original) The PCB as specified in Claim 12 wherein said channels are defined in a radial pattern.

16. (original) The PCB as specified in Claim 12 wherein said channels are defined as multiple lines.

17. (withdrawn) A method of fabricating a printed circuit board (PCB) having electrically conductive signal traces thereon, comprising the steps of:

defining and patterning a bond pad to define a channel laterally through the bond pad adapted to facilitate outgassing of bubbles generated in solder during re-flow of solder upon the bond pad.

18. (withdrawn) The method of fabricating as specified in Claim 17 wherein the bond pad is dimensioned to render the bond pad non-planar.